

Title (en)
CHEMICAL MECHANICAL PLANARIZATION (CMP) PAD CONDITIONER AND METHOD OF MAKING

Title (de)
KONDITIONIERER FÜR EIN PAD FÜR CHEMISCH-MECHANISCHE PLANARISIERUNG (CMP) UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)
CONDITIONNEUR DE TAMPON DE PLANARISATION CHIMICO-MÉCANIQUE (CMP) ET SON PROCÉDÉ DE FABRICATION

Publication
EP 2652773 A2 20131023 (EN)

Application
EP 11849399 A 20111213

Priority
• US 42256310 P 20101213
• US 2011064565 W 20111213

Abstract (en)
[origin: US2012149287A1] A method of forming a chemical mechanical planarization (CMP) pad conditioner includes placing abrasive grains on a major surface of a substrate, forming a binding composition at an exterior surface of the abrasive grains, and depositing a bonding layer over the surface of the substrate and a portion of the abrasive grains to secure the abrasive grains to the major surface of the substrate.

IPC 8 full level
H01L 21/304 (2006.01)

CPC (source: EP KR US)
B24B 53/017 (2013.01 - EP US); **B24D 3/06** (2013.01 - EP US); **B24D 18/00** (2013.01 - EP US); **H01L 21/304** (2013.01 - KR)

Citation (search report)
See references of WO 2012082702A2

Designated contracting state (EPC)
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US 201113324146 A 20111213; CN 201180062917 A 20111213; EP 11849399 A 20111213; JP 2013543411 A 20111213; KR 20137017391 A 20111213; SG 2013045018 A 20111213; TW 100144718 A 20111205; US 2011064565 W 20111213